



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-16
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ECO7*L264EA6	A	BO2A	2016-05-16
Amount	UoM	Unit type	ST ECOPACK Grade	
76.29	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for UC2843BD1			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EC07*L264E6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.181	mg	supplier	die	Silicon (Si)	7440-21-3		3.088	mg	970764	40477
				supplier	metallization	Aluminium (Al)	7429-90-5		0.038	mg	11946	498
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	4087	170
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	5973	249
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	628	26
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.021	mg	6602	275
Leadframe	Copper & its alloys	28.963	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.901	mg	963333	365723
				supplier	alloy	Iron (Fe)	7439-89-6		0.656	mg	22650	8599
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1381	524
				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1174	446
				supplier	metallization	Nickel (Ni)	7440-02-0		0.304	mg	10495	3985
				supplier	metallization	Palladium (Pd)	7440-05-3		0.010	mg	345	131
	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.009	mg	311	118
				supplier	metallization	Silver (Ag)	7440-22-4		0.009	mg	311	118
				supplier	glue	Silver (Ag)	7440-22-4		0.980	mg	879713	12846
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.056	mg	50269	734
Die attach	Other Organic Materials	1.114	mg	supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.056	mg	50269	734
				supplier	glue	Acrylate polymer	87320-05-6		0.022	mg	19749	289
				supplier	wire	Copper (Cu)	7440-50-8		0.091	mg	1000000	1193
Bonding wires	Other inorganic materials	0.091	mg	supplier	wire	Copper (Cu)	7440-50-8		0.091	mg	1000000	1193
				supplier	mold compound	Silica, vitreous	60676-86-0		36.285	mg	844996	475619
				supplier	mold compound	Epoxy resin	Proprietary		4.294	mg	99998	56285
				supplier	mold compound	Phenol resin	Proprietary		2.147	mg	49999	28143
Encapsulation	Other Organic Materials	42.941	mg	supplier	mold compound	Carbon black	1333-86-4		0.215	mg	5007	2818
				supplier	mold compound	Carbon black	1333-86-4		0.215	mg	5007	2818